

Title (en)

Device for detaching wafers from ingot support and stocking individualized wafers

Title (de)

Vorrichtung zum Abtrennen von Wafern des Halbleiterbarrensupports und zum Lagern der individualisierten Wafer

Title (fr)

Dispositif pour la mise en éléments de stockage de tranches obtenues par sciage d'un bloc

Publication

**EP 0802028 A3 19980408 (FR)**

Application

**EP 97105331 A 19970329**

Priority

CH 95696 A 19960416

Abstract (en)

[origin: EP0802028A2] The method involves placing the wafers (2) of a cut block (1) attached b a heel section (3) to s cutting support (4,5). A cutting station (6-8) has a cutter (7,15) to cut the heel and a drive (6) moves the wafers with respect to the cutter to present the wafers individually to a cutter to detach the wafers one by one from the heel sections. A collector (9,10) collects each detached wafer and places it in an empty case of the cassette. There can be a support plate (4) on which the cut block is placed and which is mounted on the cutter base.

IPC 1-7

**B28D 5/00**; **B28D 7/04**

IPC 8 full level

**B28D 1/04** (2006.01); **B28D 5/00** (2006.01); **H01L 21/304** (2006.01); **H01L 21/677** (2006.01)

CPC (source: EP)

**B28D 5/0082** (2013.01)

Citation (search report)

- [A] FR 481627 A 19161228 - FRANS HENRIK AUBERT WIELGOLASK [NO]
- [A] JP S61125767 A 19860613 - SUMITOMO METAL IND, et al
- [A] PATENT ABSTRACTS OF JAPAN vol. 018, no. 258 (M - 1606) 17 May 1994 (1994-05-17)
- [A] PATENT ABSTRACTS OF JAPAN vol. 095, no. 011 26 December 1995 (1995-12-26)

Cited by

DE102005053410B4; DE19900671A1; DE19900671C2; WO2007054525A1; DE202006020827U1

Designated contracting state (EPC)

DE FR GB IT

DOCDB simple family (publication)

**EP 0802028 A2 19971022**; **EP 0802028 A3 19980408**; **EP 0802028 B1 20030521**; CH 691169 A5 20010515; DE 69722071 D1 20030626; DE 69722071 T2 20040318; JP H1070095 A 19980310

DOCDB simple family (application)

**EP 97105331 A 19970329**; CH 95696 A 19960416; DE 69722071 T 19970329; JP 11357397 A 19970416